

What is claimed is:

1. A semiconductor device having a plurality of input terminals,
comprising:

5 a comb-shaped wiring disposed around a bonding pad which serves
as each of the input terminal, at the same potential as said bonding terminal,
said comb-shaped wiring having cavities and fingers at constant spaced
intervals;

10 a capacitive wiring disposed in facing relation to said comb-shaped
wiring and having fingers positioned respectively in said cavities of said
comb-shaped wiring in an interdigitating fashion; and

15 a resistive wiring disposed underneath said capacitive wiring and
connected to said capacitive wiring by a plurality of contacts, said resistive
wiring having ends connected to a ground potential.

20 2. A semiconductor device according to claim 1, wherein said bonding
pad is rectangular in shape, and said comb-shaped wiring and said
capacitive wiring are disposed in covering around relation to three sides of
said bonding pad.

25 3. A semiconductor device having a plurality of input terminals,
comprising:

 a comb-shaped wiring disposed around a bonding pad which serves
as each of the input terminal, at the same potential as said bonding terminal,
said comb-shaped wiring having cavities and fingers at constant spaced
intervals;

a capacitive wiring disposed in facing relation to said comb-shaped wiring and having fingers positioned respectively in said cavities of said comb-shaped wiring in an interdigitating fashion;

5 a resistive wiring disposed in a lower layer outside of a position where said capacitive wiring is disposed, and connected by a plurality of contacts to a layer in which said bonding pad is disposed, said resistive wiring having ends connected to a ground potential; and

joint wirings interconnecting said contacts and said capacitive wiring in said layer in which said bonding pad is disposed.

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4. A semiconductor device according to claim 3, wherein said bonding pad is rectangular in shape, and said comb-shaped wiring and said capacitive wiring are disposed in covering around relation to three sides of said bonding pad.

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